

## CLAIMS

1. An optical data communication module comprising:

a base board;

5 a light emitting element;

a light receiving element;

an IC chip; and

a sealing resin package,

10 wherein the light emitting element, the light receiving element, and the IC chip are mounted on the base board, and are covered by the sealing resin package,

wherein the base board is formed with a recess including an inner surface covered by a metal film which is grounded, the recess accommodating the light emitting element.

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2. The optical data communication module according to claim 1, wherein the light emitting element is an infrared rays emitting element, while the light receiving element is an infrared rays receiving element.

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3. The optical data communication module according to claim 1, wherein top surface of the metal film is higher than top of the light emitting element.

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4. The optical data communication module according to claim 1, wherein the recess is filled with a resin having elastic coefficient lower than the resin package, the resin covering

the light emitting element.

5. The optical data communication module according to claim 1, wherein the recess is an inverted trapezoidal cone having diameter that becomes smaller as proceeding toward bottom surface of the cone.